

ABSTRACT OF THE DISCLOSURE

A photosolder resist composition of the invention is characterized by containing (A) a resin containing radical polymerization groups and carboxyl groups obtained by adding 5 a cyclic ether group of a cyclic ether group-containing vinyl monomer to a carboxylic group of a radical copolymer containing at least isobornyl (meth) acrylate and a carboxyl group-containing vinyl monomer as monomer units; (B) an inorganic filler; and (C) a photocurable mixture of a polyfunctional 10 acrylic monomer (c1), a cyclic ether group-containing compound (c2), and a photopolymerization initiator (c3).